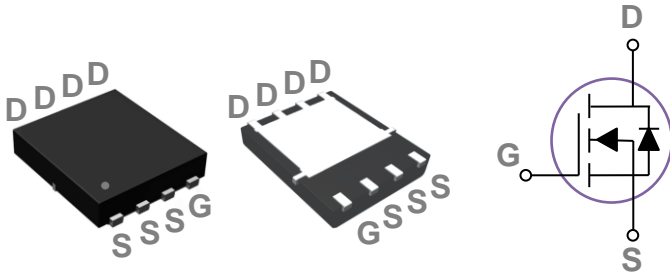


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5X6 Pin Configuration



BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
60V	17mΩ	42A

### Features

- 60V, 42A, R<sub>DS(ON)</sub> = 17mΩ @V<sub>GS</sub> = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting
- Quick Charger

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	42	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	26	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	168	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	45	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	30	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	62.5	W
	Power Dissipation – Derate above 25°C	0.5	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	2	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{GS}=10V, I_D=20A$	---	13	17	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	16	20	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.7	2.5	V
gfs	Forward Transconductance	$V_{DS}=10V, I_D=3A$	---	10	---	S

**Dynamic and switching Characteristics**

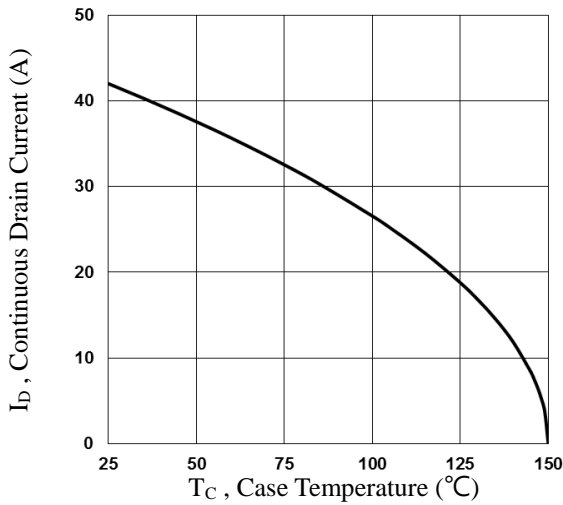
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=30V, V_{GS}=4.5V, I_D=10A$	---	13.2	26	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	4.2	9	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	6.2	12	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=15V, V_{GS}=10V, R_G=6\Omega$ $I_D=1A$	---	8.6	16	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	24.2	48	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	32.3	64	
$T_f$	Fall Time <sup>3, 4</sup>		---	7.9	16	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	1515	3000	pF
$C_{oss}$	Output Capacitance		---	120	200	
$C_{rss}$	Reverse Transfer Capacitance		---	76	120	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	1.8	3.6	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

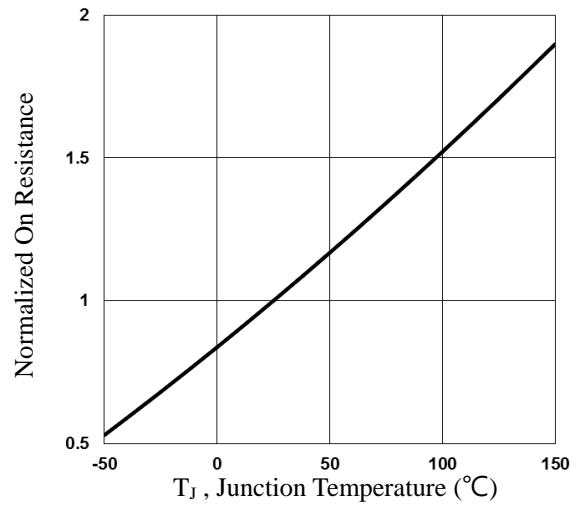
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	42	A
$I_{SM}$	Pulsed Source Current <sup>3</sup>		---	---	84	A
$V_{SD}$	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time	$V_{GS}=0V, I_S=1A, di/dt=100A/\mu s$	---	19	---	ns
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	5	---	nC

Note :

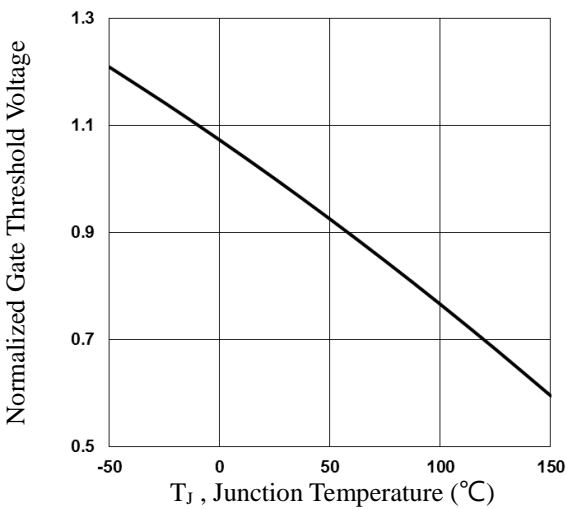
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=30A, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



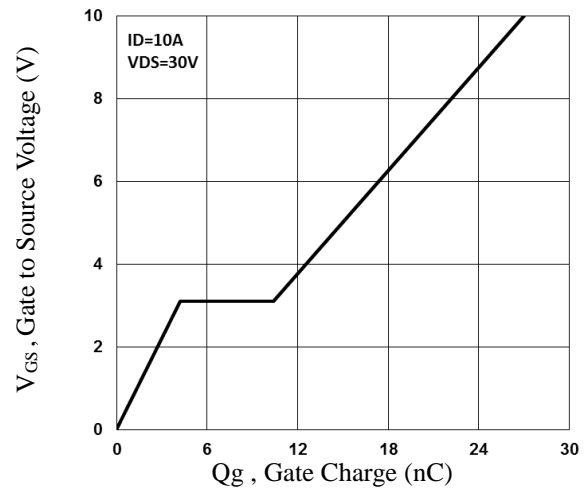
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



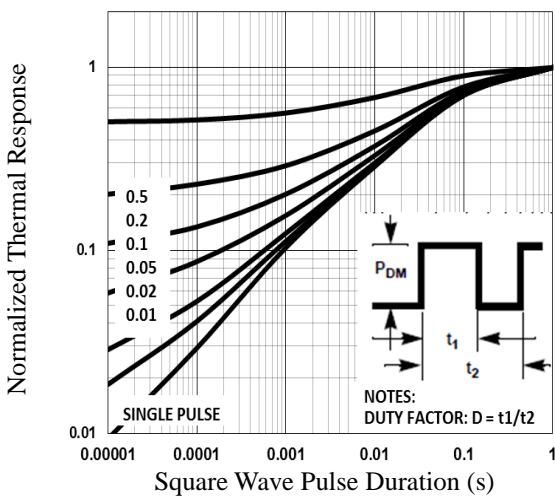
**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**



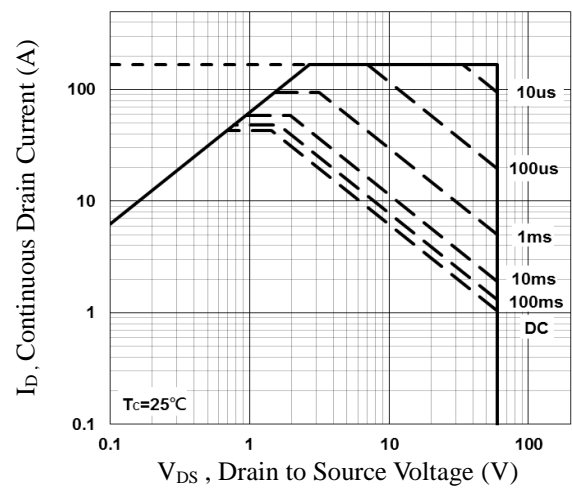
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



**Fig.4 Gate Charge Waveform**



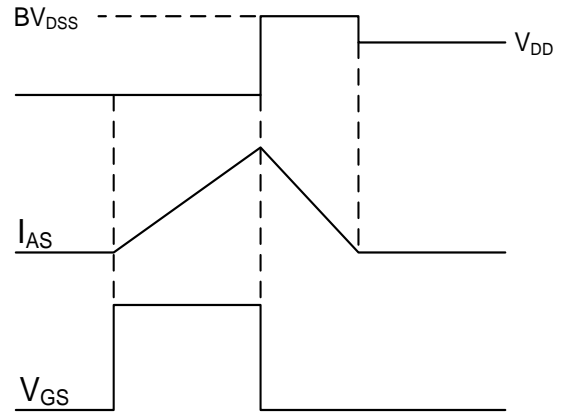
**Fig.5 Normalized Transient Response**



**Fig.6 Maximum Safe Operation Area**



**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	---	1.100	---	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°